APPARATUS AND METHOD FOR BOND FORCE CONTROL

ABSTRACT

This invention relates to an apparatus and method for providing bond force control in a die bonding operation. It comprises means for generating a primary bond force, means for generating a compensatory bond force in the same direction or opposite to said primary bond force, and means for controlling the compensatory bond force whereby a bond force comprising the sum of the primary bond force and the compensatory bond force may be controlled.

Fig. 3

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